

Product Change Notification - GBNG-28HRUQ041

Date: 19 Oct 2017
Product Category: Power Management - System Supervisors/Voltage Detectors; Voltage References
Notification subject: CCB 2840 Final Notice: Qualification of JCET as an additional assembly site for selected products of the 120K wafer technology available in 3L SOT-23 package using CuPdAu bond wire.
Notification text: **PCN Status:**
 Final notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of JCET as an additional assembly site for selected products of the 120K wafer technology available in 3L SOT-23 package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at MTAI, ATES, NSEB or UNIS using gold (Au) bond wire and G600 molding compound material

Post Change:

Assembled at MTAI, ATES, NSEB and UNIS using gold (Au) bond wire and G600 molding compound material or assembled at JCET using palladium coated copper with gold flash (CuPdAu) bond wire and ELER-8-100HFE molding compound material.

Pre and Post Change Summary:

	Pre Change				Post Change			
Assembly Site	Microchip Technology Thailand (MTAI)	Millennium Microtech (Shanghai) CO., LTD (ATES)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Unisem (M) Berhad Perak, Malaysia (UNIS)	Microchip Technology Thailand (MTAI)	Millennium Microtech (Shanghai) CO., LTD (ATES)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Unisem (M) Berhad Perak, Malaysia (UNIS)
Paddle size	64x38	64x38	72x40	57x35	64x38	64x38	72x40	57x35
Lead frame material	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194
Wire material	Au	Au	Au	Au	Au	Au	Au	Au
Die attach material	8390A	84-1 LMISR4	84-1 LMISR4	84-1 LMISR4	8390A	84-1 LMISR4	84-1 LMISR4	84-1 LMISR4
Mold compound material	G600	G600	G600	G600	G600	G600	G600	G600

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying JCET as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

November 19, 2017 (date code: 1747)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2017				-->	October 2017					November 2017			
	14	15	16	17		40	41	42	43	44	45	46	47	48
Initial PCN Issue Date		X												
Qual Report Availability							X							
Final PCN Issue Date							X							
Estimated Implementation Date												X		

Qualification Report:Method to Identify Change:

Traceability code

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

April 12, 2017: Issued initial notification.

October 19, 2017: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on November 19, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_GBNG-28HRUQ041_Affected CPN.pdf](#)
- [PCN_GBNG-28HRUQ041_Qual Report.pdf](#)
- [PCN_GBNG-28HRUQ041_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_GBNG-28HRUQ041
CATALOG_PART_NBR
MCP100T-270I/TT
MCP100T-270I/TTAAA
MCP100T-300I/TT
MCP100T-315I/TT
MCP100T-450I/TT
MCP100T-460I/TT
MCP100T-475I/TT
MCP100T-485I/TT
MCP101T-270I/TT
MCP101T-300I/TT
MCP101T-315I/TT
MCP101T-450I/TT
MCP101T-460I/TT
MCP101T-475I/TT
MCP101T-485I/TT
MCP102T-195I/TT
MCP102T-195I/TTV01
MCP102T-240E/TT
MCP102T-270E/TT
MCP102T-300E/TT
MCP102T-315E/TT
MCP102T-450E/TT
MCP102T-475E/TT
MCP120T-270I/TT
MCP120T-300I/TT
MCP120T-315I/TT
MCP120T-450I/TT
MCP120T-450I/TTS01
MCP120T-460I/TT
MCP120T-475I/TT
MCP120T-485I/TT
MCP121T-195I/TT
MCP121T-240E/TT
MCP121T-270E/TT
MCP121T-300E/TT
MCP121T-315E/TT
MCP121T-315E/TTAAA
MCP121T-416E/TT
MCP121T-450E/TT
MCP121T-475E/TT
MCP130T-270I/TT
MCP130T-300I/TT
MCP130T-315I/TT

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Affected Catalog Part Numbers (CPN)

MCP130T-450I/TT
MCP130T-450I/TTV02
MCP130T-460I/TT
MCP130T-475I/TT
MCP130T-485I/TT
MCP131T-195I/TT
MCP131T-240E/TT
MCP131T-250E/TT
MCP131T-270E/TT
MCP131T-300E/TT
MCP131T-315E/TT
MCP131T-450E/TT
MCP131T-475E/TT
MCP1525T-I/TT
MCP1541T-I/TT